

N-Channel Enhancement Mosfet , ESD Protected

GENERAL DESCRIPTION

The ME7804-G N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching , and low in-line power loss are needed in a very small outline surface mount package.

FEATURES

- $R_{DS(ON)} \leq 16m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} \leq 25m\Omega @ V_{GS}=4.5V$

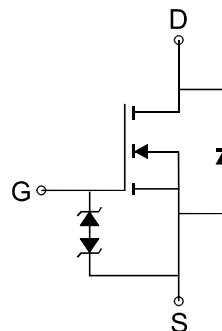
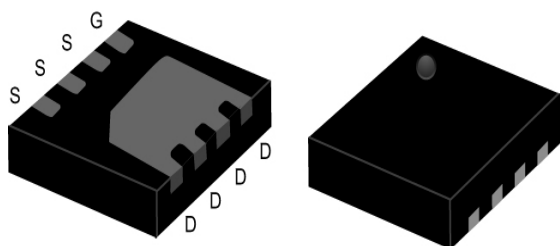
APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- Load Switch
- DSC
- ESD Protected

PIN CONFIGURATION

(DFN 3.3x3.3)

Top View



Ordering Information: ME7804-G (Green product-Halogen free)

Absolute Maximum Ratings (T_j=25°C Unless Otherwise Noted)

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	V _{DSS}	30	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (t _J =150°C)	I _D	T _A =25°C	12.2
		T _A =70°C	9.7
Pulsed Drain Current	I _{DM}	50	A
Maximum Power Dissipation	P _D	T _A =25°C	3.8
		T _A =70°C	2.4
Operating Junction Temperature	T _J	-55 to 150	°C
Thermal Resistance-Junction to Ambient	R _{θJa}	33	°C/W

* The device mounted on 1in² FR4 board with 2 oz copper



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Electrical Characteristics ($T_A=25^{\circ}\text{C}$ Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
STATIC						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1		3	V
I_{GSS}	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 16V$			± 10	μA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V$			1	μA
$R_{DS(on)}$	Drain-Source On-State Resistance ^a	$V_{GS}=10V, I_D=10A$		13	16	m Ω
		$V_{GS}=4.5V, I_D=5A$		19	25	
V_{SD}	Diode Forward Voltage	$I_S=9A, V_{GS}=0V$		0.8		V
DYNAMIC						
Q_g	Total Gate Charge (10V)	$V_{DS}=15V, V_{GS}=10V, I_D=10A$		18		nC
Q_g	Total Gate Charge (4.5V)			8.8		
Q_{gs}	Gate-Source Charge			4.2		
Q_{gd}	Gate-Drain Charge			3.7		
C_{iss}	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1MHz$		729		pF
C_{oss}	Output Capacitance			94		
C_{rss}	Reverse Transfer Capacitance			29		
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$		0.9		Ω
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=25V, R_L=25\Omega$ $R_{GEN}=6\Omega, V_{GS}=10V$		14		ns
t_r	Turn-On Rise Time			9.5		
$t_{d(off)}$	Turn-Off Delay Time			44		
t_f	Turn-Off Fall Time			5.7		

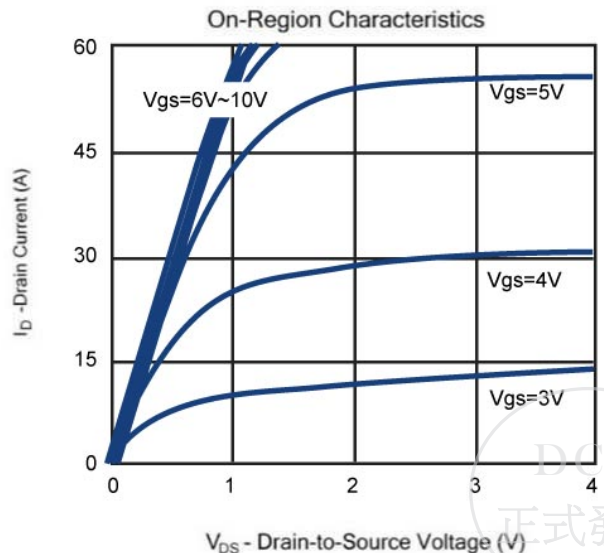
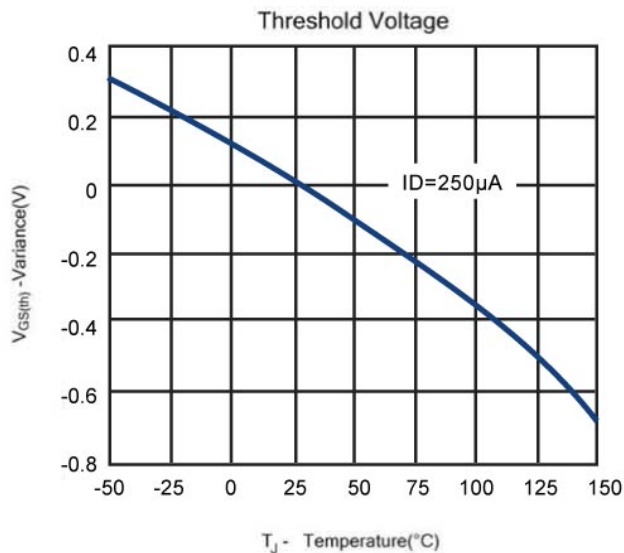
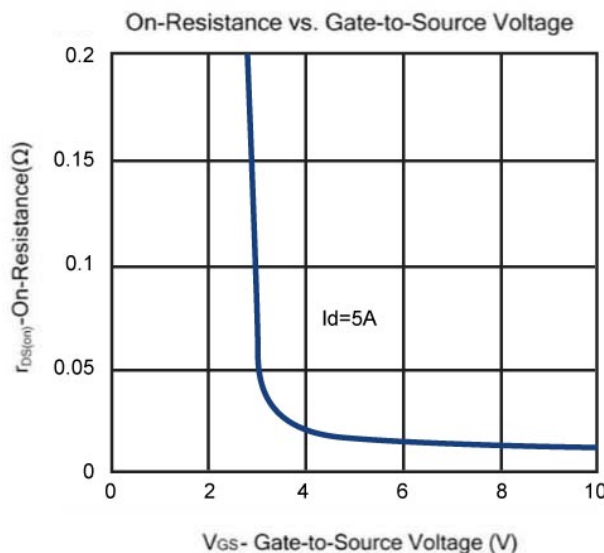
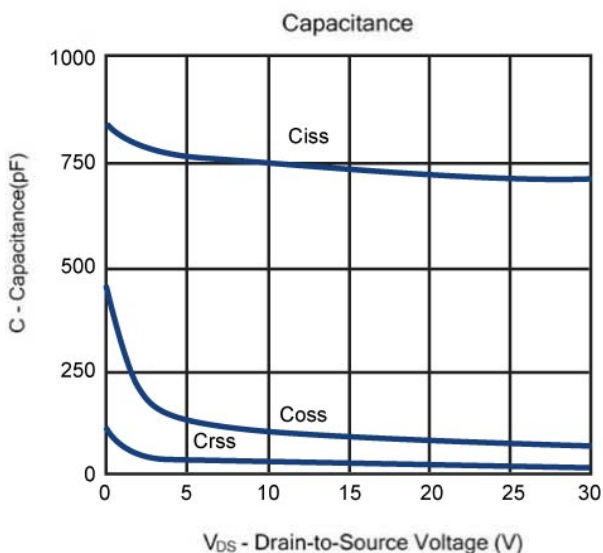
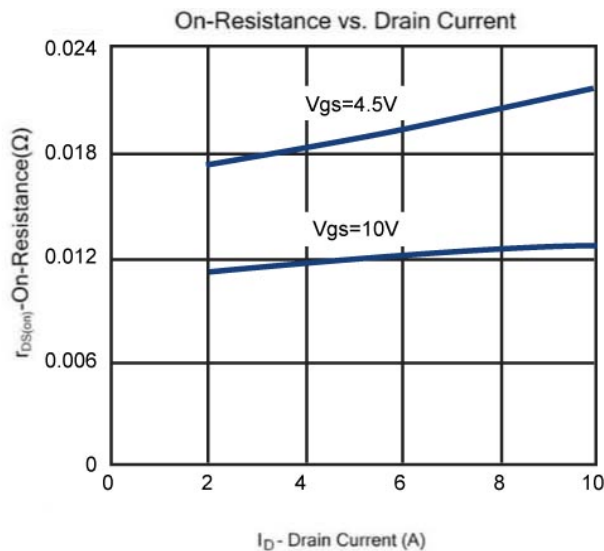
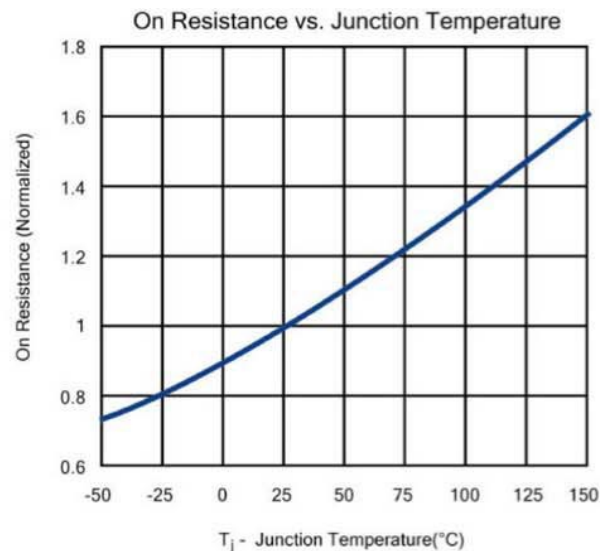
 Notes: a. Pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$, Guaranteed by design, not subject to production testing.

b. Matsuki reserves the right to improve product design, functions and reliability without notice.



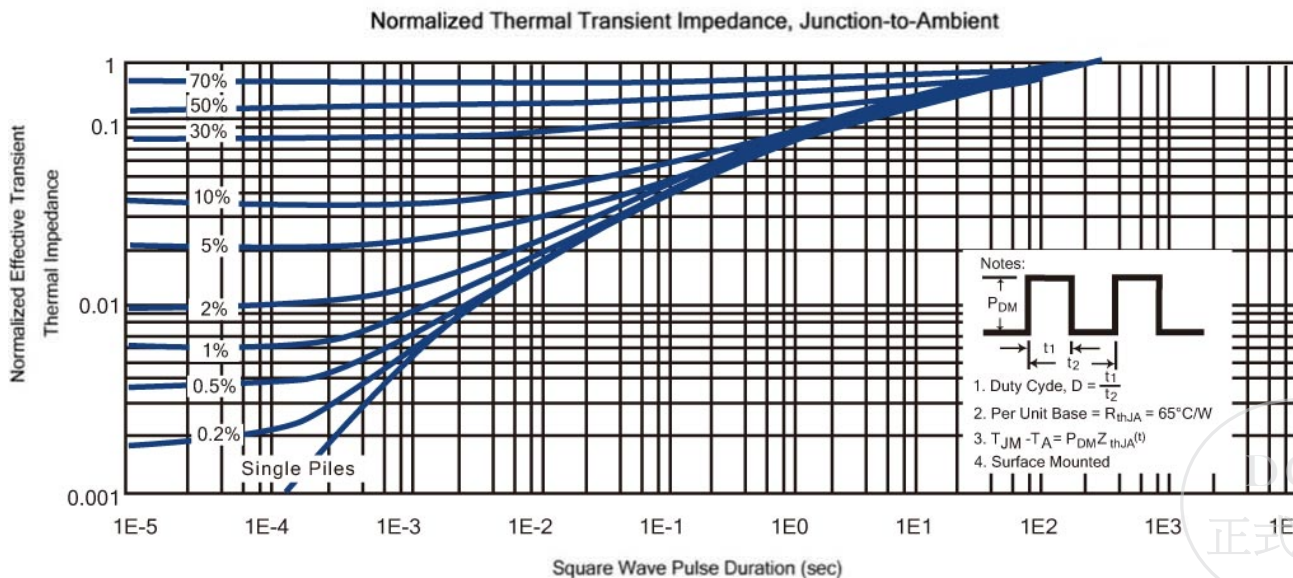
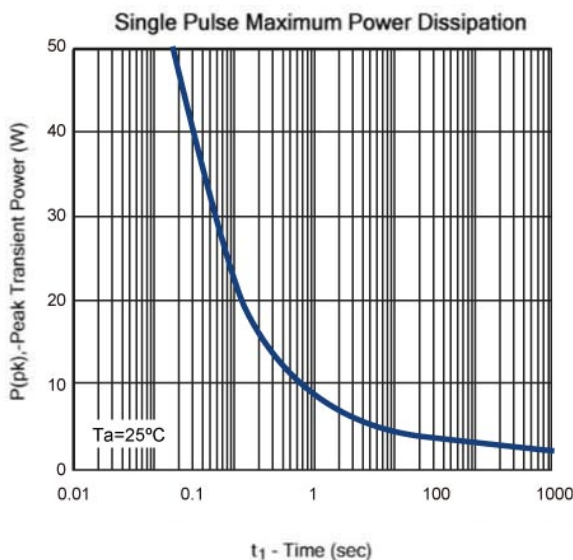
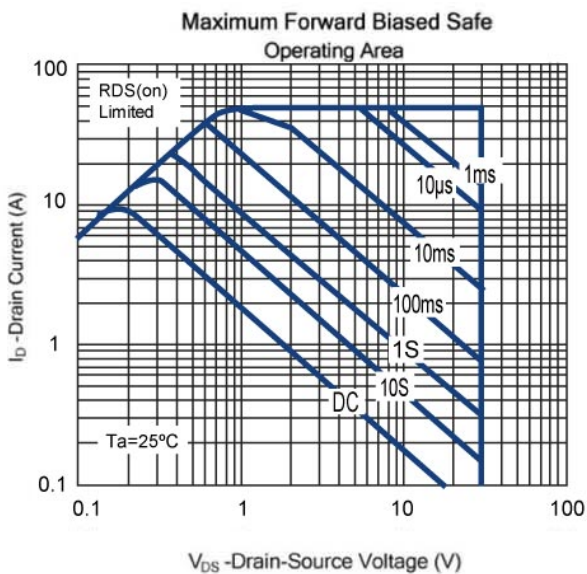
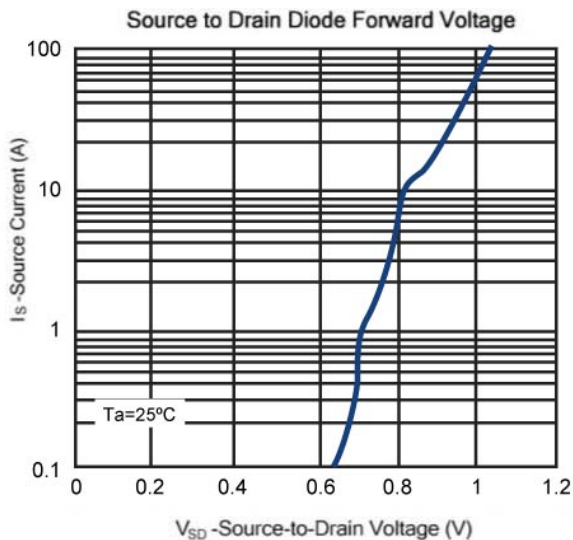
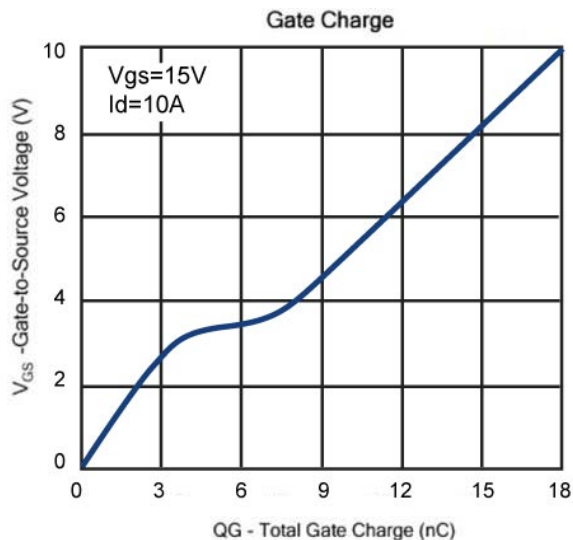
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Typical Characteristics (T_J =25°C Noted)

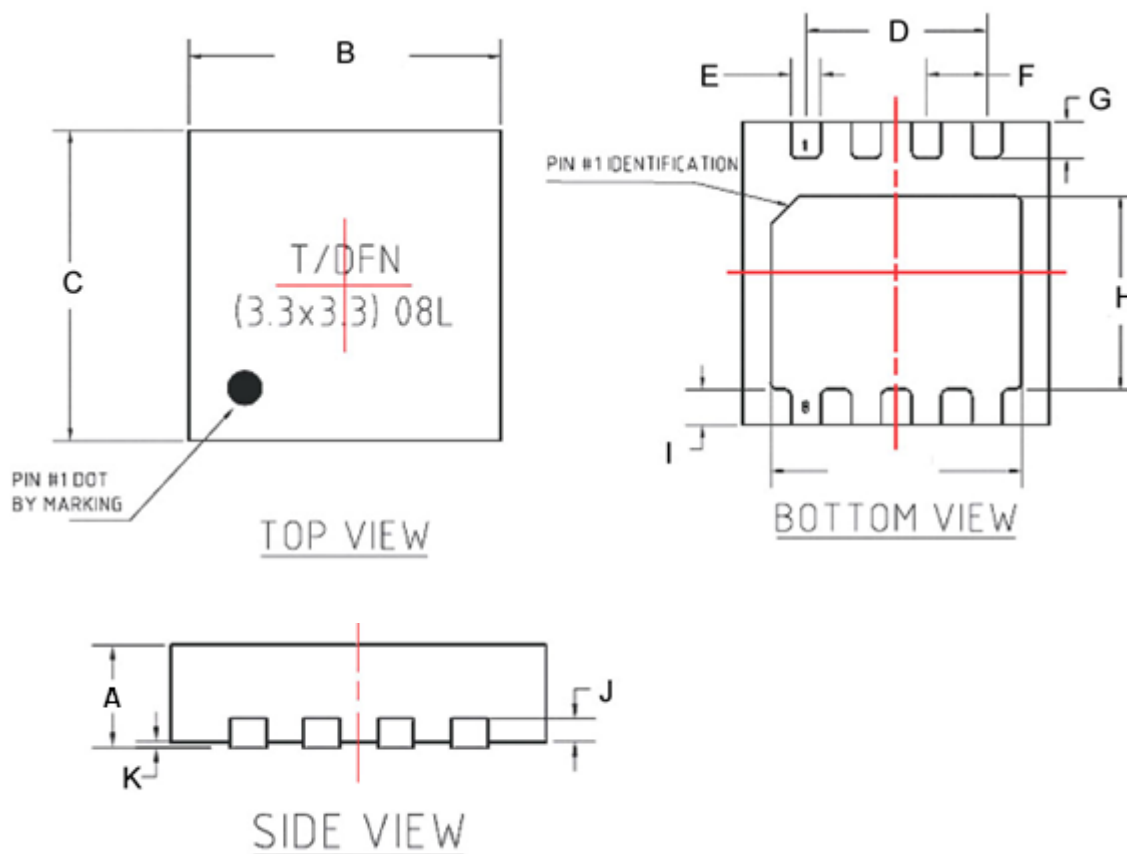


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Typical Characteristics (T_J =25°C Noted)



DFN 3.3x3.3 Package Outline



SYMBOL	MILLIMETERS (mm)	
	MIN	MAX
A	0.700	1.000
B	3.250	3.350
C	3.250	3.350
D	1.95REF.	
E	0.270	0.370
F	0.65BSC	
G	0.350	0.450
H	2.050	2.150
I	0.385	0.395
J	0.195	0.211
K	0.000	0.050
L	2.650	2.750

